

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	22	laser same scrib\$3 with (depth deep\$4) with micron	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/02 10:56
L3	7	laser same scrib\$3 with (depth deep\$4) with micron and (saw \$3 cut\$4 dic\$4) with (wafer semiconduct\$4 silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/02 10:58
L4	20	scrib\$3 with (depth deep\$4) with micron and (saw\$3 cut\$4 dic \$4) with (wafer semiconduct\$4 silicon) and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/02 11:00
L5	13	4 not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/02 11:00
L6	22	scrib\$3 with (depth deep\$4) with (micron ? m) and (saw\$3 cut\$4 dic\$4) with (wafer semiconduct\$4 silicon) and laser not 5 not 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/02 11:06
S1	2	((("5552345") or ("6562698")).PN.	USPAT; USOCR	OR	OFF	2009/02/01 13:08
S2	2	"20030052098"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:08
S4	3	((("6257224") or ("4811722") or ("6291317"))).PN.	USPAT; USOCR	OR	OFF	2009/02/01 13:10
S5	4	S1 S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:11

S6	4	"2001026435"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:12
S9	1	S6 and ablat\$4 same saw\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:17
S10	1929	laser with (cut\$4 scribe\$4 etch\$4 ablat\$4) same (wafer semiconductor\$3 silicon) and (cool\$4 liquid blow\$3) with thermal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:38
S11	24	laser with (cut\$4 scribe\$4 etch\$4 ablat\$4) same (wafer semiconductor\$3 silicon) and (cool\$4 liquid blow\$3) with reduce\$5 with thermal\$4 with (cut\$4 scribe\$4 etch\$4 ablat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:38
S12	119	laser with (cut\$4 scribe\$4 etch\$4 ablat\$4) and (cool\$4 liquid blow\$3) with reduce\$5 with thermal\$4 same (cut\$4 scribe\$4 etch\$4 ablat\$4) not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:43
S13	129	laser with (cut\$4 scribe\$4 etch\$4 ablat\$4) and (cool\$4 liquid blow\$3) with (reduce\$5 minimum\$8 eliminate\$4) near\$3 thermal\$4 same (cut\$4 scribe\$4 etch\$4 ablat\$4) not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:44
S14	33	laser with (cut\$4 scribe\$4 etch\$4 ablat\$4) same (cool\$4 liquid blow\$3) with (reduce\$5 minimum\$8 eliminate\$4) near\$3 thermal\$4 same (cut\$4 scribe\$4 etch\$4 ablat\$4) not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:44

S15	8	laser with (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3) same (cool\$4 liquid blow\$3) with (reduce\$5 minimize\$8 eliminate\$4) near3 thermal\$4 same (cut\$4 scribe\$4 etch\$4 ablate\$4) not S11 and (silicon wafer) with (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 13:46
S16	31	laser and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3) and (cool\$4 liquid blow\$3) and (reduce\$5 minimize\$8 eliminate\$4) and thermal\$4	JPO	OR	ON	2009/02/01 13:53
S17	4	laser and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3) and (cool\$4 liquid blow\$3) and (reduce\$5 minimize\$8 eliminate\$4) and thermal\$4 and (silicon wafer)	JPO	OR	ON	2009/02/01 13:53
S18	1	laser and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) and (coolant liquid) and (reduce\$5 minimize\$8 eliminate\$4) with thermal\$4 and (silicon wafer)	JPO	OR	ON	2009/02/01 13:56
S19	1	(laser energy beam) and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) and (coolant liquid) and (reduce\$5 minimize\$8 eliminate\$4) with thermal\$4 and (silicon wafer)	JPO	OR	ON	2009/02/01 13:57
S20	81	(laser energy beam) and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) with (cool\$3 liquid thermal\$4) and (reduce\$5 minimize\$8 eliminate\$4) and (silicon wafer)	JPO	OR	ON	2009/02/01 13:58

S21	25	(laser energy beam) and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) with (cool\$3 liquid thermal\$4) with (reduce\$5 minimize\$8 eliminate\$4) and (silicon wafer)	JPO	OR	ON	2009/02/01 13:59
S22	471	(laser energy beam) with (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) same (silicon wafer) and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) with (cool\$3 liquid thermal\$4) near\$4 (reduce\$5 minimize\$8 eliminate\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 14:06
S23	3	(laser energy beam) with (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) same (silicon wafer) and (cut\$4 scribe\$4 etch\$4 ablate\$4 die\$3 groove\$3 street) with (cool\$3 liquid) with thermal\$4 near\$4 (reduce\$5 minimize\$8 eliminate\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 14:07
S24	28	scribe\$4 with wafer and laser and gas with (water liquid) with (cool\$4 thermal\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 14:14
S25	7	scribe\$4 with wafer and laser and gas with (water liquid) with (cool\$4 thermal\$4) with (laser scribe\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 14:15

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